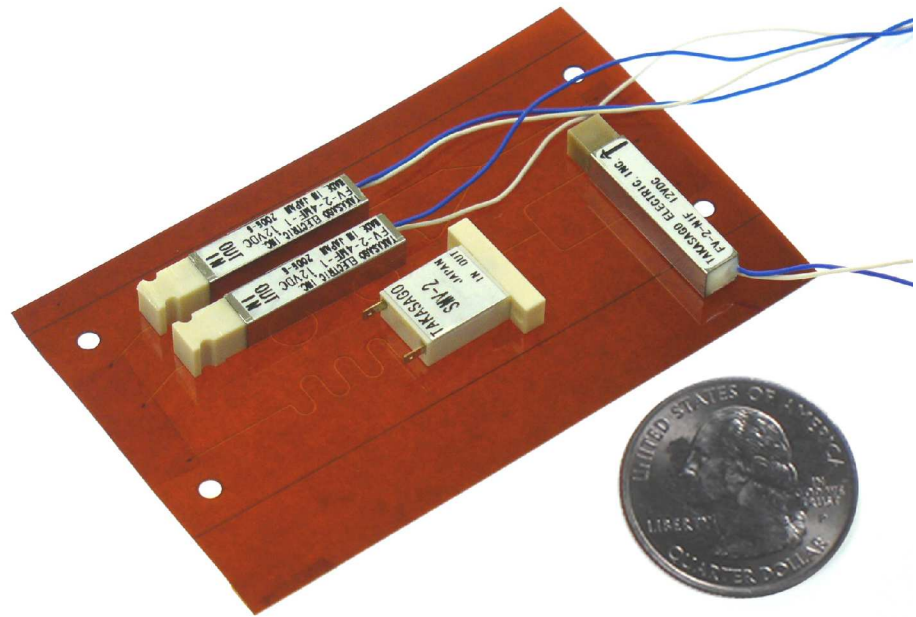


Film Manifold (patent pending)

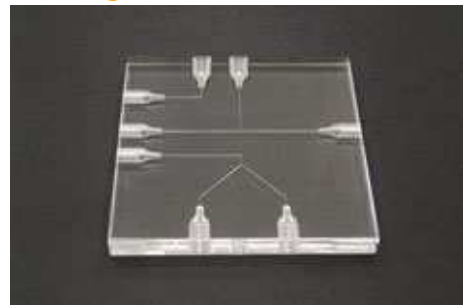
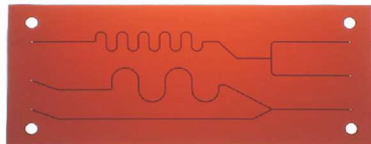


The Film Manifold is small, lightweight and made by engraving precise channels in layers of bonded chemically-inert Polyimide (PI) etc. Compared to the current Acrylic Bonded Manifold, the Film Manifold exceeds in chemical inertness and can be significantly smaller.

Furthermore, with a minimum layer thickness of only 75 μ m, the Film Manifold has the following notable characteristics.

1. Bendable.
2. Easy control of channel temperature.

Comparison with Acrylic Bonding Manifold



Film Manifold

Acrylic Bonding Manifold

Note: The Film Manifold is developed in cooperation with SOHKiCo., Ltd. Specifications and other details may be changed without prior notice.

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